Part No. 95-132I25 - QFP to PGA Adapter for JEDEC 132 Position, .025 [.64] Pitch

FEATURES:

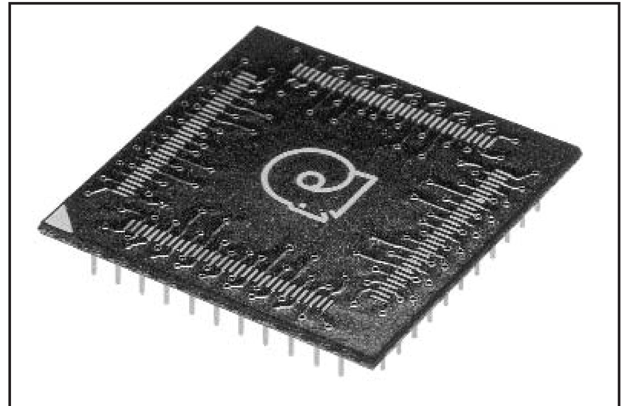
- Convert surface mount QFP packages to a 13 x 13 PGA footprint.
- Reduce costs by using less expensive QFP packages to replace PGA footprints in existing designs.
- Pins are mechanically fastened and soldered to board using Aries' patented process, creating a reliable electrical connection and rugged contact.
- Consult factory for panelized form or for mounting of consigned chips.

SPECIFICATIONS:

- Adapter body is FR-4 with 1 ounce minimum Copper traces.
- Pads are bare Copper protected with Entek® by Enthone or immersion white tin to eliminate coplanarity concerns and solder bridges associated with hot air solder leveling.
- Pins are Brass Alloy 360 1/2 hard per UNS C36000 ASTM-B16-00.
- Pin plating is 200µ [5.08µm] min. Tin per ASTM B 545 Type 1 or Tin/Lead 93/7 per ASTM B 545 over 100µ [2.54µm] Nickel per SAE-AMS-QQ-N-290.
- Operating temperature=221°F [105°C].

MOUNTING CONSIDERATIONS:

- Suggested PCB hole size=.028 ± .003 [.71 ± .08] dia.
- Will plug into standard PGA sockets.



Note: Aries specializes in custom design and production. In addition to the standard products shown on this page, special materials, platings, sizes, and configurations can be furnished, depending on quantities. Aries reserves the right to change product specifications without notice.

ORDERING INFORMATION

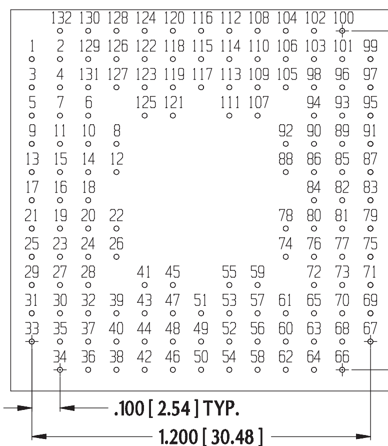
Specify Part No. 95-132I25
-or-
95-132I25-P for panelized form
when ordering

Specify Part Number 132-PGM13072-30
for wire wrap PGA socket

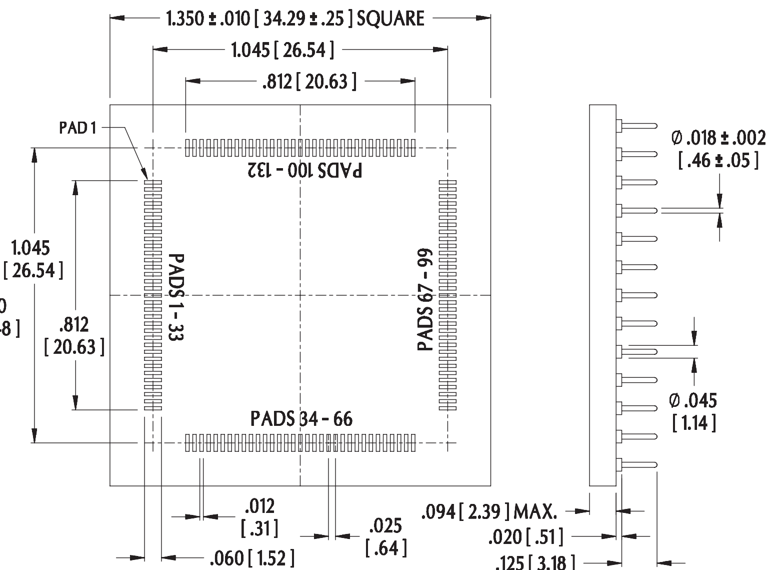
ALL DIMENSIONS: INCHES [MILLIMETERS]

Tolerances:

Row-to-row:	± .003 [± .08]
Pin-to-pin:	± .003 [± .08] non-cumulative
All others:	± .005 [.13] unless otherwise specified



X-RAY VIEW TOP SIDE
QFP PAD ASSIGNMENT



TOP (QFP) SIDE

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